

Description

The Si2324DS uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 100V I_D = 3 A

 $R_{DS(ON)} < 248m\Omega @ V_{GS}=10V$

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

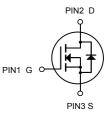
Product ID	Pack	Brand	Qty(PCS)
Si2324DS	SOT-23	HXY MOSFET	3000

Absolute Maximum Ratings (TC=25°C unless otherwise specified)

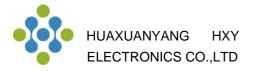
Symbol	Parameter	Rating			
Vds	Drain-Source Voltage	100	V		
Vgs	Gate-Source Voltage	Gate-Source Voltage ±20			
I _D @T _A =25°C	Continuous Drain Current, V _{GS} @ 10V ¹	Continuous Drain Current, V _{GS} @ 10V ¹ 3			
I _D @T _A =70°C	Continuous Drain Current, V _{GS} @ 10V ¹	as @ 10V ¹ 1			
Ідм	Pulsed Drain Current ²	5	A		
PD@TA=25°C	Total Power Dissipation ³	1	W		
Тѕтс	Storage Temperature Range	-55 to 150	°C		
TJ	Operating Junction Temperature Range	-55 to 150	°C		
R ₀ JA	Thermal Resistance Junction-ambient ¹	125	°C/W		
Rejc	Thermal Resistance Junction-Case ¹	80	°C/W		







N-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BVDSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100			V
∆BV _{DSS} /∆T _J	BVDSS Temperature Coefficient	Reference to 25°C , ID=1mA		0.067		V/°C
		V _{GS} =10V , I _D =1A		210	248	
RDS(ON)	Static Drain-Source On-Resistance ²	V _{GS} =4.5V , I _D =0.5A		244	290	mΩ
VGS(th)	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	1.5	2.5	V
$\bigtriangleup V_{GS(th)}$	V _{GS(th)} Temperature Coefficient			-4.2		mV/°C
IDSS	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			1	uA
IDSS	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25°C			5	uA
lgss	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =1A		2.4		S
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.8	5.6	
Qg	Total Gate Charge (10V)			9.7	13.6	
Qgs	Gate-Source Charge			1.6	2.2	nC
Qgd	Gate-Drain Charge	-		1.7	2.4	
Td(on)	Turn-On Delay Time			1.6	3.2	
Tr	Rise Time	V _{DD} =50V , V _{GS} =10V ,		19	34	
Td(off)	Turn-Off Delay Time			13.6	27	ns
T _f	Fall Time	I _D =1A		19	38	
Ciss	Input Capacitance			508	711	
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		29	41	pF
Crss	Reverse Transfer Capacitance			16.4	23	
ls	Continuous Source Current ^{1,4}				1.2	Α
lsм	Pulsed Source Current ^{2,4}	−V _G =V _D =0V , Force Current			5	A
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
trr	Reverse Recovery Time			14		nS
Qrr	Reverse Recovery Charge	IF=1A , dI/dt=100A/µs , Tյ=25℃		9.3		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle $\leq 2\%$

3. The power dissipation is limited by 150°C junction temperature

4 .The data is theoretically the same as I_{D} and I_{DM} , in real applications , should be limited by total power dissipation.



Typical Characteristics

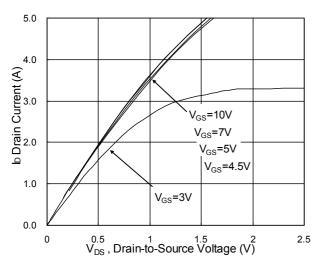


Fig.1 Typical Output Characteristics

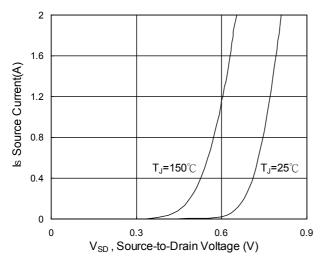


Fig.3 Forward Characteristics of Reverse

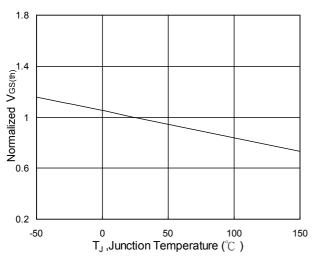


Fig.5 Normalized $V_{\text{GS(th)}}\,vs.\,T_{\text{J}}$

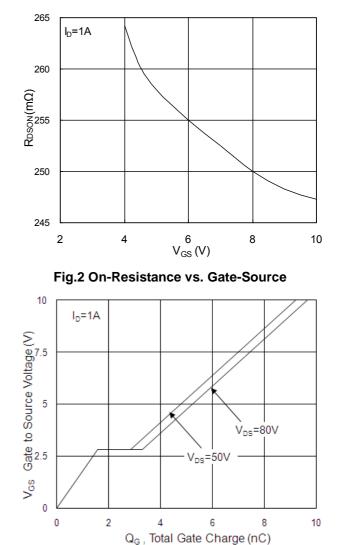


Fig.4 Gate-Charge Characteristics

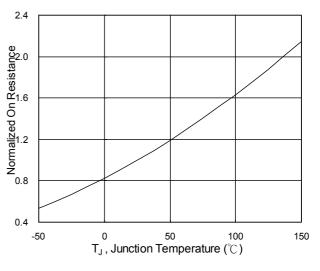


Fig.6 Normalized R_{DSON} vs. T_{J}



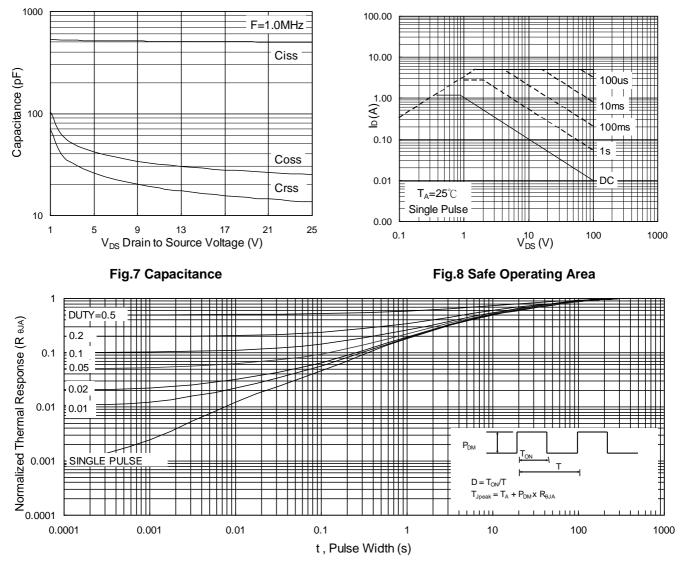


Fig.9 Normalized Maximum Transient Thermal Impedance

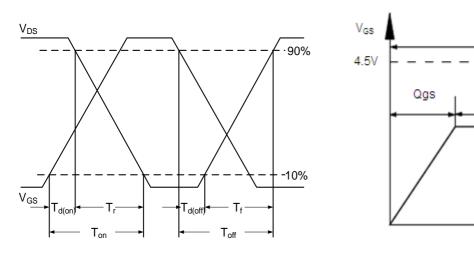


Fig.10 Switching Time Waveform



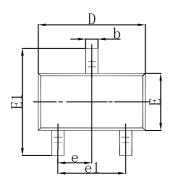
Qg

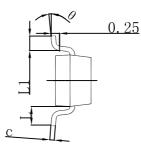
Qgd

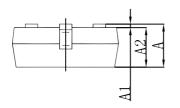
Charge



SOT-23 Package Outline Dimensions

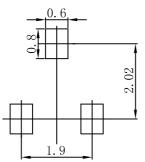






Symbol	Dimensions In Millimeters		Dimensions In Inches		
	Min	Max	Min	Max	
Α	0.900	1.150	0.035	0.045	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.050	0.035	0.041	
b	0.300	0.500	0.012	0.020	
С	0.080	0.150	0.003	0.006	
D	2.800	3.000	0.110	0.118	
Е	1.200	1.400	0.047	0.055	
E1	2.250	2.550	0.089	0.100	
е	0.950 TYP		0.037 TYP		
e1	1.800	2.000	0.071	0.079	
L	0.550 REF		0.022 REF		
L1	0.300	0.500	0.012	0.020	
θ	0°	8°	0°	8°	

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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